



# SOT886

**XSON6: plastic extremely thin small outline package; no leads; 6 terminals; 0.6 mm pitch; 1 mm x 1.45 mm x 0.5 mm body**

9 January 2017

Package information

## 1. Package summary

<b>Dimensions (mm)</b>	1.45 x 1 x 0.5
<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	XSON6
<b>Package outline version code</b>	SOT886
<b>Manufacturer package code</b>	SOT886
<b>Package type industry code</b>	XSON6
<b>Package outline version description</b>	XSON6: plastic extremely thin small outline package; no leads; 6 terminals; 0.6 mm pitch; 1 mm x 1.45 mm x 0.5 mm body
<b>Package style descriptive code</b>	XSON (extremely thin small outline; no leads)
<b>Package body material type</b>	P
<b>JEDEC package outline code</b>	MO-252
<b>Handling precautions</b>	IC26_CHAPTER_3_2000
<b>Thermal design considerations</b>	SC18_1999_CHAPTER_5_2
<b>Mounting method type</b>	S (surface mount)
<b>Generic mounting and soldering information</b>	AN10365_3
<b>Reflow soldering footprint</b>	SOT886_fr
<b>Package life cycle status</b>	REL
<b>Major version date</b>	18-9-2008
<b>Minor version date</b>	14-5-2012
<b>Security status</b>	COMPANY PUBLIC
<b>Modified date</b>	15-11-2012
<b>Issue date</b>	22-7-2004
<b>Web publication date</b>	28-11-2012
<b>Initial web publication date</b>	8-3-2011
<b>Customer specific indicator</b>	N
<b>Maturity</b>	Product
<b>Package author</b>	Nair Deepa
<b>Package approver</b>	Nair Deepa

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A <sub>2</sub>	package height	-	-	0.5	-	mm
A	seated height	-	-	0.5	0.5	mm



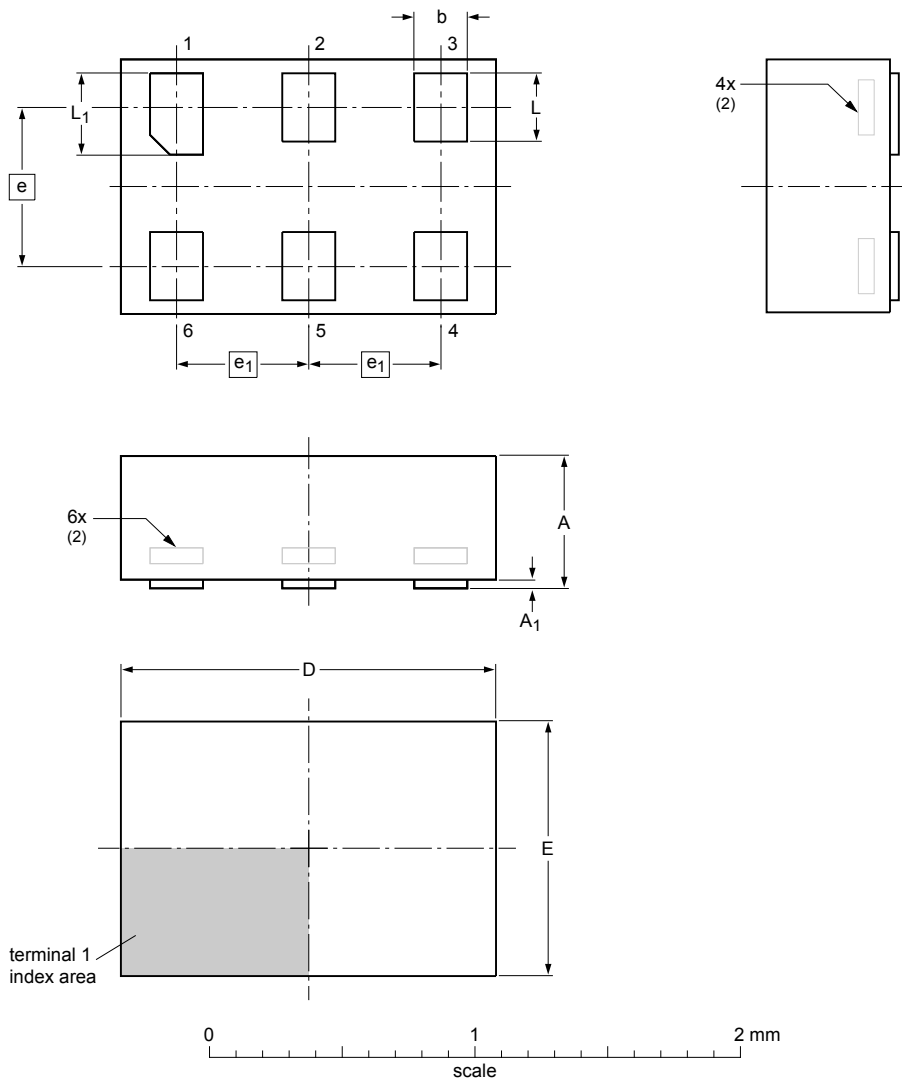
XSON6: plastic extremely thin small outline package; no leads; 6 terminals; 0.6 mm pitch; 1 mm x 1.45 mm x 0.5 mm body

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1.4	-	1.45	1.5	mm
E	package width		0.95	-	1	1.05	mm
e	nominal pitch		-	-	0.6	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	6	-	

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## 2. Package outline

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm SOT886



Dimensions (mm are the original dimensions)

Unit	A <sup>(1)</sup>	A <sub>1</sub>	b	D	E	e	e <sub>1</sub>	L	L <sub>1</sub>
mm	max	0.5	0.04	0.25	1.50	1.05		0.35	0.40
	nom		0.20	1.45	1.00	0.6	0.5	0.30	0.35
	min		0.17	1.40	0.95			0.27	0.32

Notes

- Including plating thickness.
- Can be visible in some manufacturing processes.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT886		MO-252			-04-07-22- 12-01-05

Fig. 1. Package outline XSON6 (SOT886)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; 0.6 mm pitch; 1 mm x 1.45 mm x 0.5 mm body

### 3. Soldering

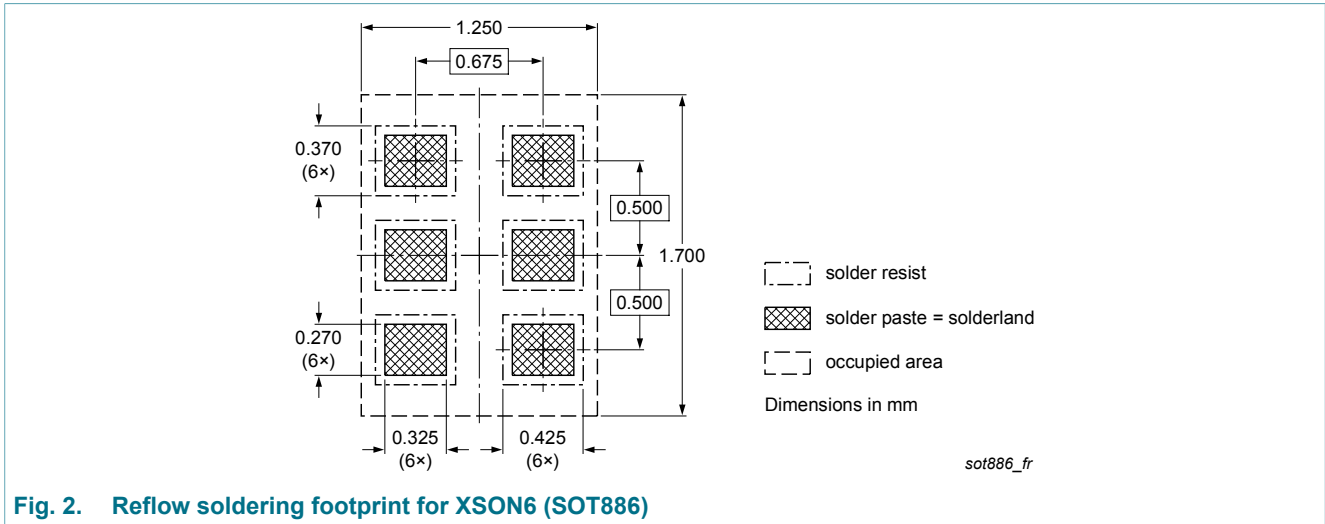


Fig. 2. Reflow soldering footprint for XSON6 (SOT886)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; 0.6 mm pitch; 1 mm x 1.45 mm x 0.5 mm body

## 4. Legal information

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